SN74ALVCH16374 16-BIT EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

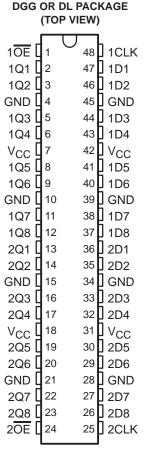
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- Member of the Texas Instruments
 Widebus™ Family
- EPIC[™] (Enhanced-Performance Implanted CMOS) Submicron Process
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

description

This 16-bit edge-triggered D-type flip-flop is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH16374 is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. It can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels at the data (D) inputs. \overline{OE} can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.



OE does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16374 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

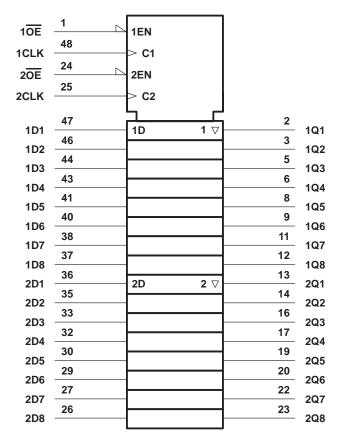
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FUNCTION TABLE (each flip-flop)

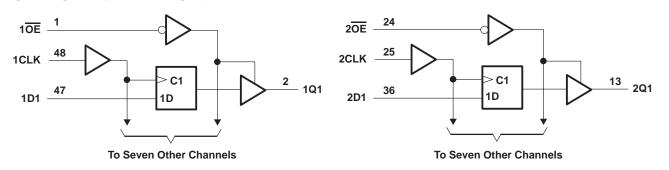
	INPUTS	OUTPUT	
OE	CLK	D	Q
L	1	Н	Н
L	\uparrow	L	L
L	H or L	Χ	Q ₀
Н	X	Χ	Z

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	
Output voltage range, VO (see Notes 1 and 2)	\dots -0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through each V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 3): DGG package	89°C/W
DL package	94°C/W
Storage temperature range, T _{sto}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 4.6 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
Vcc	Supply voltage		1.65	3.6	V	
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V _{CC}			
\vee_{IH}	H High-level input voltage L Low-level input voltage Input voltage Output voltage OH High-level output current Low-level output current	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2			
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$		
VIL	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V	
	V _{CC} = 2.7			0.8		
٧ı	Input voltage		0	Vcc	V	
٧o	Output voltage		0	VCC	V	
		V _{CC} = 1.65 V		-4		
	L Low-level input voltage Input voltage Output voltage High-level output current Low-level output current	V _{CC} = 2.3 V		-12	A	
ЮН		V _{CC} = 2.7 V		-12	mA	
		V _{CC} = 3 V		-24		
		V _{CC} = 1.65 V		4		
١.	Low-level output current	V _{CC} = 2.3 V		12	mA	
lOL		V _{CC} = 2.7 V		12		
		V _{CC} = 3 V		24		
Δt/Δν	Input transition rise or fall rate	•		10	ns/V	
TA	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CO	ONDITIONS	Vcc	MIN	TYP [†]	MAX	UNIT
		I _{OH} = -100 μA		1.65 V to 3.6 V	V _{CC} -0.	.2		
		I _{OH} = -4 mA		1.65 V	1.2			
$VOH \begin{tabular}{ c c c c c c c c c c c c c c c c c c c$								
Vон				2.3 V	1.7			V
		I _{OH} = -12 mA		2.7 V	2.2			
				3 V	2.4			
		I _{OH} = -24 mA		3 V	2			
		I _{OL} = 100 μA		1.65 V to 3.6 V			0.2	
		I _{OL} = 4 mA		1.65 V			0.45	
\/		I _{OL} = 6 mA		2.3 V			0.4	V
VOL		1- 40 mA		2.3 V			0.7	V
		IOF = 15 WY		2.7 V			0.4	
		I _{OL} = 24 mA	3 V			0.55		
Ц		V _I = V _{CC} or GND		3.6 V			±5	μΑ
		V _I = 0.58 V		1.65 V	25			
		V _I = 1.07 V	1.65 V	-25				
		V _I = 0.7 V		2.3 V	45			
I _I (hold)		V _I = 1.7 V		2.3 V	-45			μΑ
` ´		V _I = 0.8 V		3 V	75			
		V _I = 2 V		3 V	-75			
		V _I = 0 to 3.6 V [‡]		3.6 V			±500	
loz		$V_O = V_{CC}$ or GND		3.6 V			±10	μΑ
ICC		$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			40	μΑ
Δlcc		One input at V _{CC} – 0.6 V,	Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μΑ
Ci	Control inputs Data inputs	V _I = V _{CC} or GND		3.3 V		3 6		pF
Co	Outputs	V _O = V _{CC} or GND		3.3 V		7		pF

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

		V _{CC} = 1.8 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency		§		150		150		150	MHz
t _W	Pulse duration, CLK high or low	§		3.3		3.3		3.3		ns
t _{su}	Setup time, data before CLK↑	§		2.1		2.2		1.9		ns
t _h	Hold time, data after CLK↑	§		0.6	·	0.5		0.5		ns

[§] This information was not available at the time of publication.



[‡] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
	(INPOT)	(0011-01)	MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}			†		150		150		150		MHz
t _{pd}	CLK	Q		†	1	5.3		4.9	1	4.2	ns
t _{en}	ŌĒ	Q		†	1	6.2		5.9	1	4.8	ns
t _{dis}	ŌĒ	Q		†	1	5.3		4.7	1.2	4.3	ns

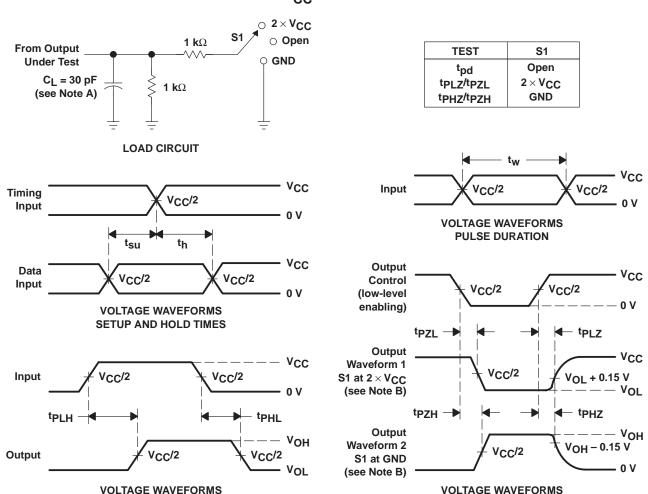
[†] This information was not available at the time of publication.

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V V _{CC} = 2.5 V V _{CC} = 3		V _{CC} = 3.3 V	UNIT		
	FARAWIETER		1E31 CONDITIONS	TYP	TYP	TYP	UNIT	
<u> </u>	Power dissipation	Outputs enabled	C ₁ = 50 pF. f = 10 MHz	†	31	30	pF	
Cpd	capacitance	Outputs disabled	$C_L = 50 \text{ pF}, f = 10 \text{ MHz}$	†	16	18	þг	

[†] This information was not available at the time of publication.

PARAMETER MEASUREMENT INFORMATION V_{CC} = 1.8 V



- NOTES: A. C_I includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \ \Omega$, $t_f \leq$ 2 ns. $t_f \leq$ 2 ns.

ENABLE AND DISABLE TIMES

- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.

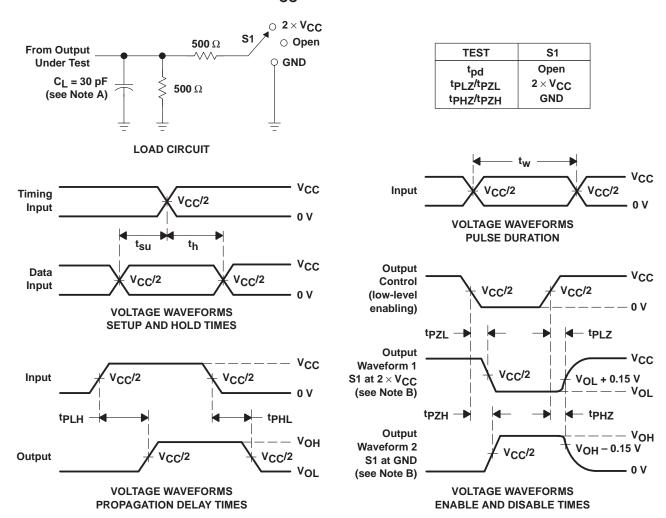
PROPAGATION DELAY TIMES

- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



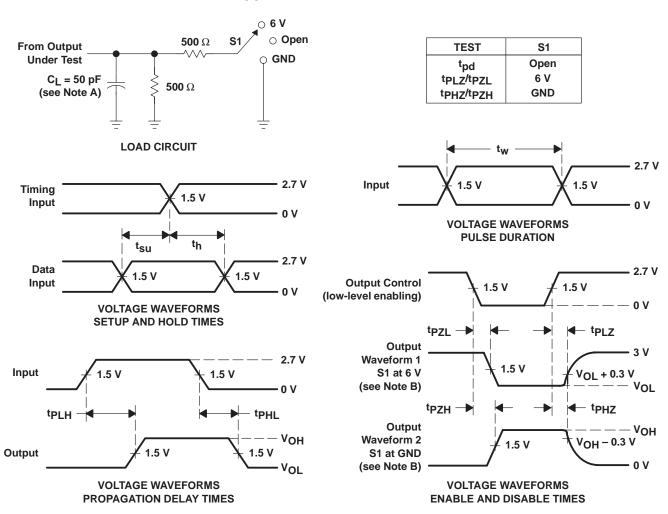
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq 2$ ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms

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PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \, \Omega$, $t_r \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 3. Load Circuit and Voltage Waveforms



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